

## Description

TF400P10K uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

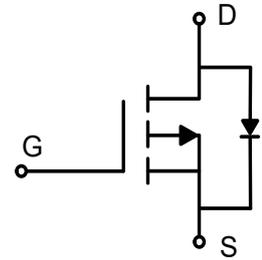


## Features

- $V_{DS} = -100V$  ,  $I_D = -40A$   
 $R_{DS(on)} = 40m\Omega$  Typ@  $V_{GS} = -10V$   
 $R_{DS(on)} = 43m\Omega$  Typ@  $V_{GS} = -4.5V$
- Extremely Low Switching Loss
- Excellent Stability and Uniformity
- Low Gate Charge
- 100% EAS Guaranteed

## Applications

- Power Management Switches
- DC/DC Converter



## Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	-100	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25^\circ C$	$I_D$	-40	A
	$T_C = 100^\circ C$		-24	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	-110	A
Single Pulse Avalanche Energy <sup>2</sup>		<b>EAS</b>	325	mJ
Total Power Dissipation	$T_C = 25^\circ C$	$P_D$	105	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	65	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	1.5	$^\circ C/W$



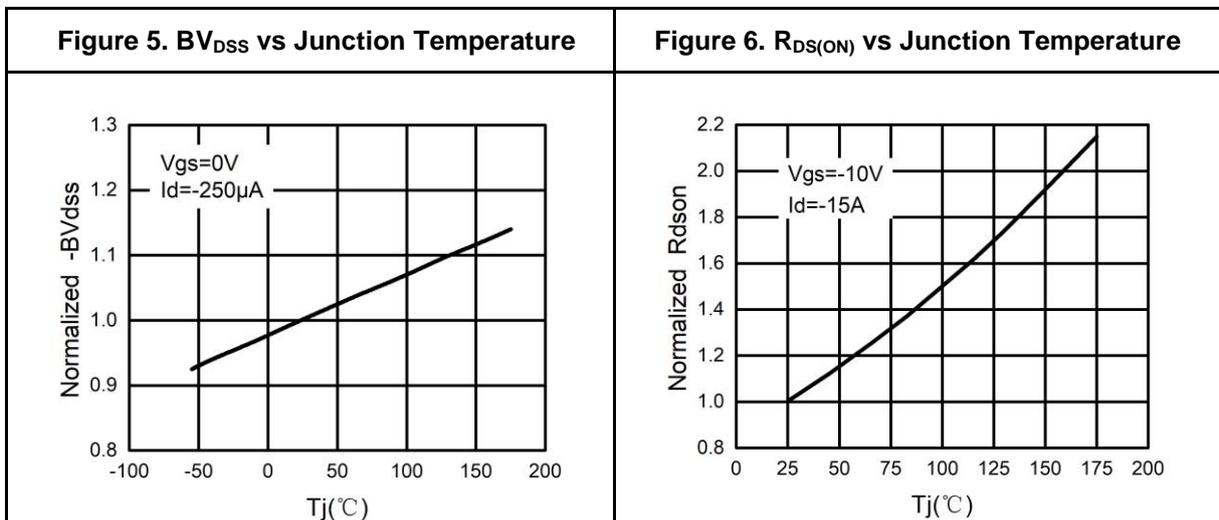
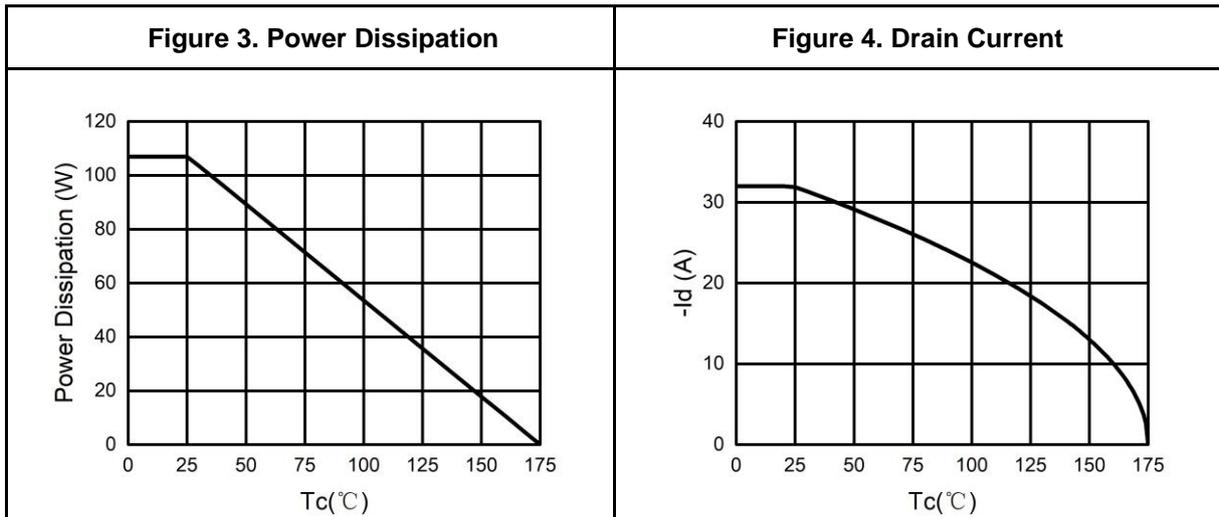
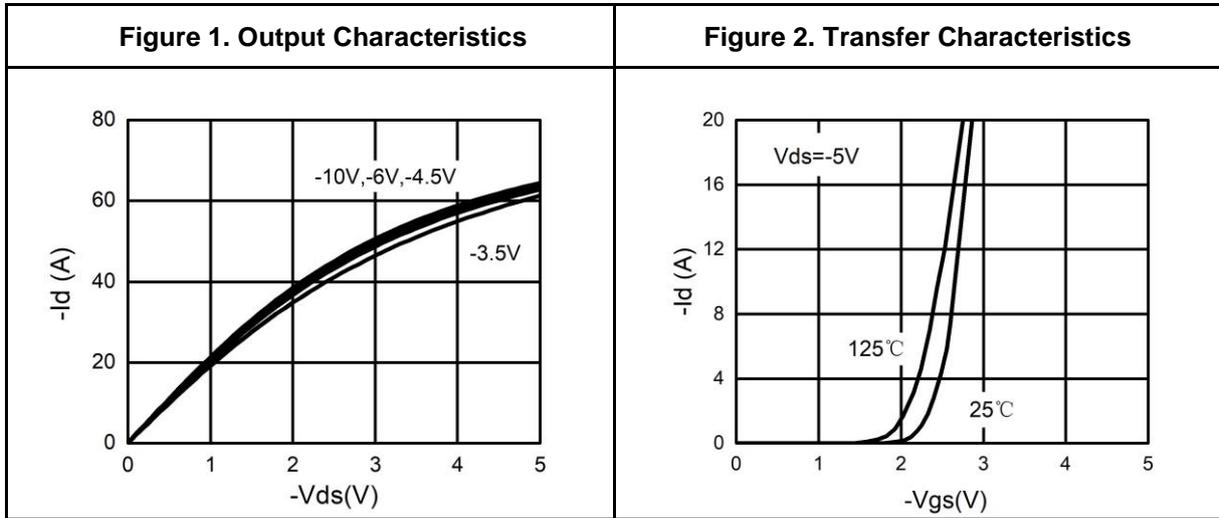
**Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)**

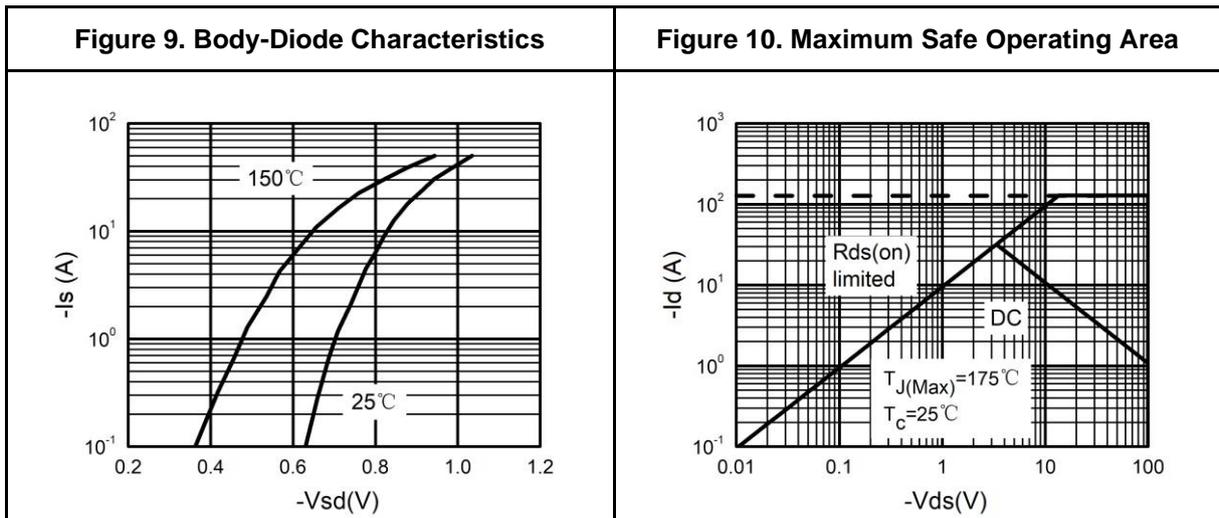
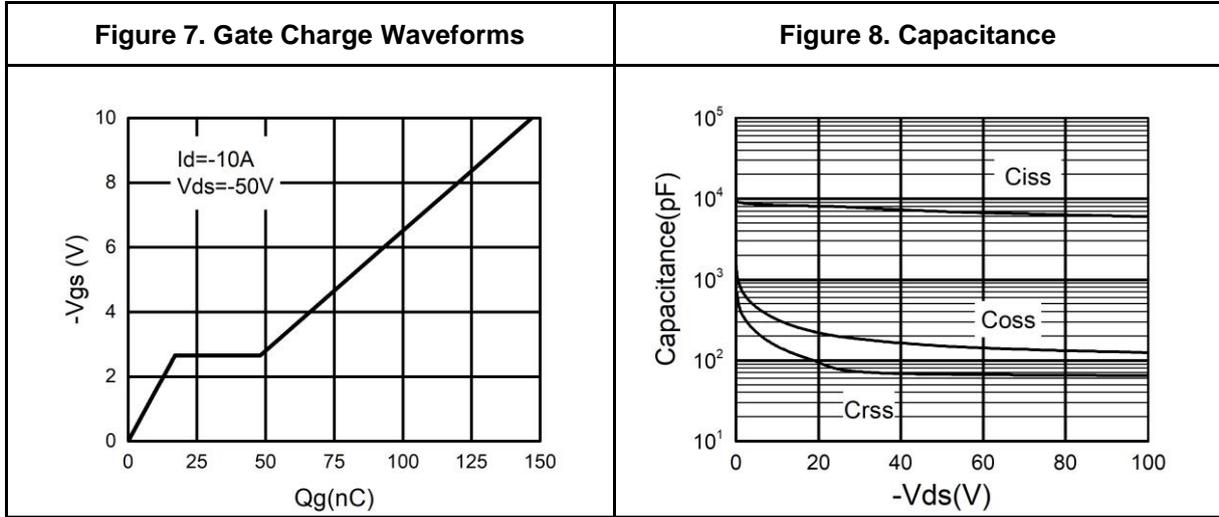
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	<b>V<sub>(BR)DSS</sub></b>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-100	-	-	V
Gate-body Leakage current	<b>I<sub>GSS</sub></b>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> = 25°C	V <sub>DS</sub> = -100V, V <sub>GS</sub> = 0V	-	-	-1	μA
	T <sub>J</sub> = 100°C		-	-	-100	
Gate-Threshold Voltage	<b>V<sub>GS(th)</sub></b>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.7	-2.5	V
Drain-Source On-Resistance <sup>4</sup>	<b>R<sub>DS(on)</sub></b>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -20A	-	40	50	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A	-	43	55	
Forward Transconductance <sup>4</sup>	<b>g<sub>fs</sub></b>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -20A	-	45	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	<b>C<sub>iss</sub></b>	V <sub>DS</sub> = -25V, V <sub>GS</sub> = 0V, f = 1MHz	-	8056	-	pF
Output Capacitance	<b>C<sub>oss</sub></b>		-	195	-	
Reverse Transfer Capacitance	<b>C<sub>rss</sub></b>		-	70	-	
Gate Resistance	<b>R<sub>g</sub></b>	f = 1MHz	-	4	-	Ω
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	<b>Q<sub>g</sub></b>	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -50V, I <sub>D</sub> = -10A	-	147	-	nC
Gate-Source Charge	<b>Q<sub>gs</sub></b>		-	17	-	
Gate-Drain Charge	<b>Q<sub>gd</sub></b>		-	31	-	
Turn-On Delay Time	<b>t<sub>d(on)</sub></b>	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -50V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = -10A	-	13	-	ns
Rise Time	<b>t<sub>r</sub></b>		-	64	-	
Turn-Off Delay Time	<b>t<sub>d(off)</sub></b>		-	36	-	
Fall Time	<b>t<sub>f</sub></b>		-	52	-	
Body Diode Reverse Recovery Time	<b>t<sub>rr</sub></b>	I <sub>F</sub> = -15A, dI/dt = 100A/μs	-	72	-	ns
Body Diode Reverse Recovery Charge	<b>Q<sub>rr</sub></b>		-	120	-	nC
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	<b>V<sub>sD</sub></b>	I <sub>S</sub> = -20A, V <sub>GS</sub> = 0V	-	-	-1.2	V
Continuous Source Current	T <sub>C</sub> = 25°C	<b>I<sub>s</sub></b>	-	-	-35	A

Notes:

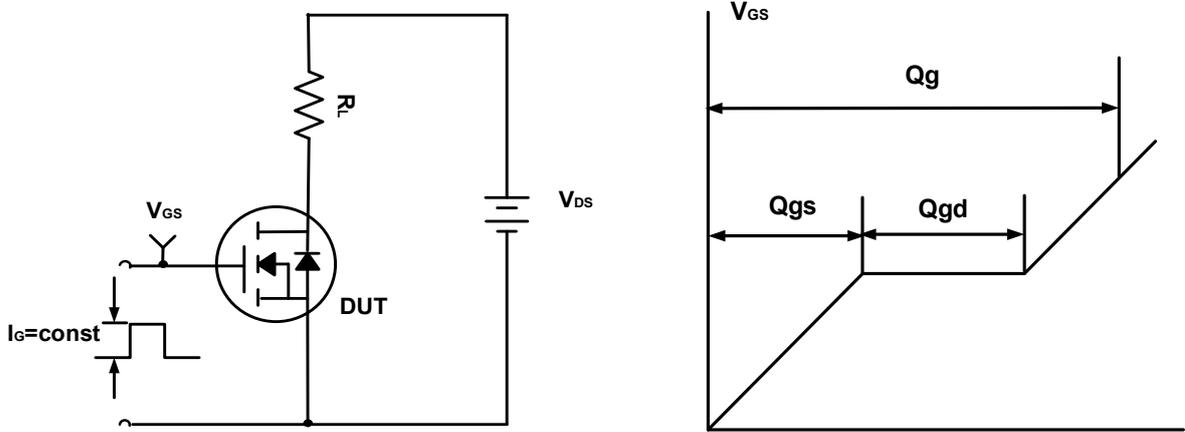
1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub> = 150°C.
2. The EAS data shows Max. rating . The test condition is V<sub>DD</sub> = -50V, V<sub>GS</sub> = -10V, L = 0.5mH, I<sub>AS</sub> = -30A
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test..

**Typical Electrical And Thermal Characteristics (Curves)**

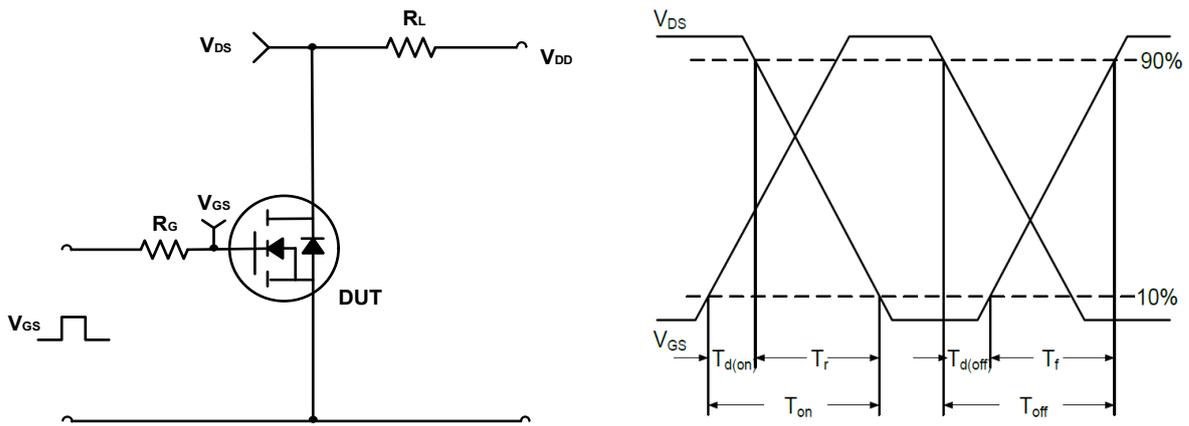




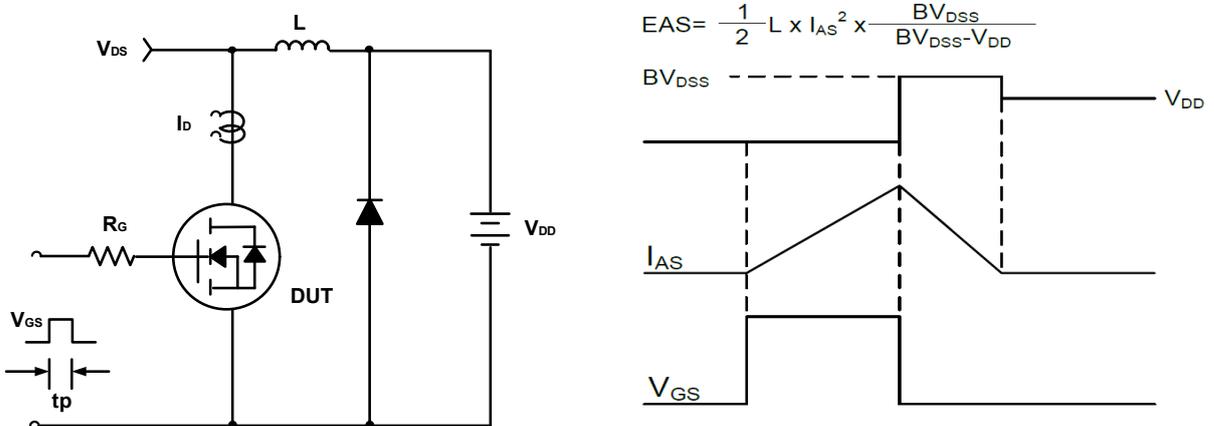
**Test Circuit**



**Figure A. Gate Charge Test Circuit & Waveforms**



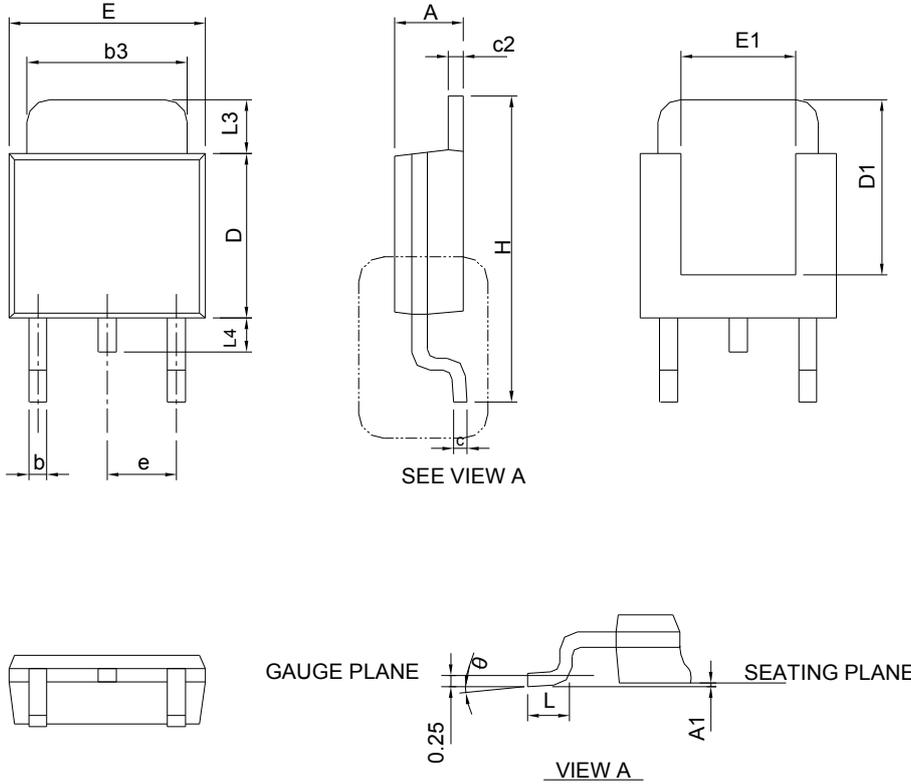
**Figure B. Switching Test Circuit & Waveforms**



**Figure C. Unclamped Inductive Switching Circuit & Waveforms**

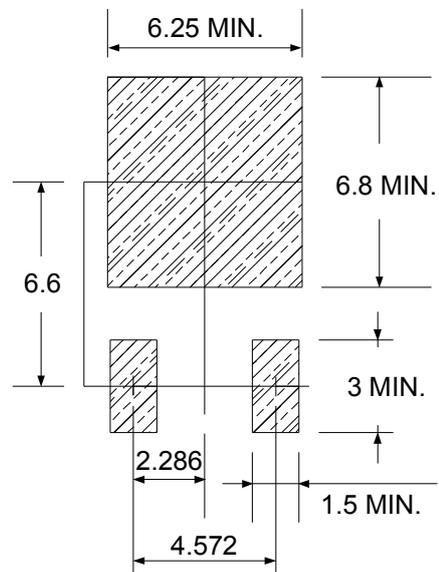
**Package Information**

TO-252



SYMBOL	TO-252			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
θ	0°	8°	0°	8°

**RECOMMENDED LAND PATTERN**



UNIT: mm